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Index the Papernor's Reduction Act of 1995, no paraons are required to respond to a collection of information unless it constitue a valid GMS covered number. Substitute for form 1449A/PTO Complete il Known INFORMATION DISCLOSURE **Application Number** 09/845881 STATEMENT BY APPLICANT April 30, 2001 Filing Date Use as many sheets as necessary) Vu, Quat **First Named Inventor** 282T 2829 **Group Art Unit** MAR 2 2 2004 **Examiner Name** Cruz, Lourdes Attorney Docket No: 884.384US1 Sheet 1 of 1

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